



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Atty. Docket

REINHOLD WIMBERGER FRIEDL ET AL

PHN 16,224

Serial No. 09/024,637

Group Art Unit: 2841

Filed: February 17, 1998

Examiner: T. Dinh

Title: SYNTHETIC RESIN CAPPING LAYER ON A PRINTED CIRCUIT

Commissioner for Patents
Washington, D.C. 20231

AMENDMENT

Sir:

In response to the non-final Official Action dated December 26, 2000, please amend the above-identified application as follows:

IN THE SPECIFICATION

Page 8, in the paragraph beginning on line 29, change as follows:

Subsequently, the circuit is accommodated in an injection
D' mould composed of two halves. In the closed state, the mould defines a cavity the shape of which corresponds to the outside of the capping layer 2 to be formed. In fact, this shape is independent of the shape of the circuit, with the regions which should not be covered by the capping layer, such as the electric connections, of course being masked by the mould. After the injection mould has been closed, a foam-forming reactive injection-